Layer Stackup: Set Dielectric 1 & Dielectric 3 thickness so that 10mil wide trace=50Ω

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric1	FR-4	8.00mil	4.8	
5	MidLayer1	Copper	1.40mil		
6	Dielectric2	FR-4	39.60mil	4.8	
7	MidLayer2	Copper	1.40mil		
8	Dielectric3	FR-4	8.00mil	4.8	
9	Bottom Layer	Copper	1.40mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

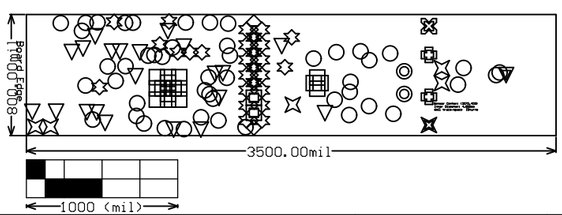
Symbol	Quantity	Finished Hole Size	Plated	Hole Type
▽	1	39.37mil (1.000mm)	NPTH	Round
◇	2	31.00mil (0.787mm)	NPTH	Slot
◘	2	31.00mil (0.787mm)	NPTH	Slot
✽	4	31.00mil (0.787mm)	NPTH	Slot
✖	1	31.00mil (0.787mm)	NPTH	Slot
✖	1	31.00mil (0.787mm)	NPTH	Slot
✿	2	31.00mil (0.787mm)	NPTH	Slot
□	17	7.87mil (0.200mm)	PTH	Round
○	48	8.00mil (0.203mm)	PTH	Round
▽	21	14.00mil (0.356mm)	PTH	Round
✿	23	28.00mil (0.711mm)	PTH	Round
✖	5	40.00mil (1.016mm)	PTH	Round
✪	2	43.31mil (1.100mm)	PTH	Round
	129 Total			

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
800MIL X 3500MIL

Number of Layers : 4
MIN. TRACK WIDTH: 6 MIL
MIN. CLEARANCE: 6 MIL
MIN. VIA PAD SIZE: 20 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
COPPER THICKNESS (FINISHED):
OUTER: [X] 1.4MIL (1oz) [ ] 2MIL (1.4oz) [ ] 2.8MIL (2oz)
INNER SIGNAL: [X] 1.4MIL (1oz) [ ] 2.8MIL (2oz) [ ] N/A
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [ ] OTHER
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS --> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK



TEXAS INSTRUMENTS

PROJECT TITLE: LDC1101EVM
DESIGNED FOR: Public Release
FILE NAME: SV601159B.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SV601159	REV: B	SVN REV: Not In VersionControl
LAYER NAME = [illegible]ions			
PLOT NAME = Fabrication Drawing	GENERATED : 5/22/2015 1:29:21 PM	TEXAS INSTRUMENTS	

Texas Instruments (TI) and/or its licensors do not warrant the accuracy or completeness of this specification or any information contained therein. TI and/or its licensors do not warrant that this design will meet the specifications, will be suitable for your application or fit for any particular purpose, or will operate in an implementation. TI and/or its licensors do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your application.

ENGINEER:	LAYOUT BY:
Chris Oberhauser	Chris Oberhauser
SCALE: 1.00	ALTIUM DESIGNER VERSION: 14.3.17.42447